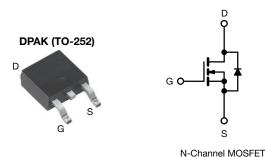
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



| PRODUCT SUMMARY | | | |
|---------------------------------------|----------------------------|--|--|
| V_{DS} (V) at T_J max. | 650 | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V 1.3 | | |
| Q _g max. (nC) | 7.5 | | |
| Q _{gs} (nC) | 1 | | |
| Q _{gd} (nC) | 3 | | |
| Configuration | Single | | |

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) R_{on} x Q_g
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

| ORDERING INFORMATION | |
|---------------------------------|-----------------|
| Package | DPAK (TO-252) |
| Lead (Pb)-free and halogen-free | SiHD1K4N60E-GE3 |

| PARAMETER | | | SYMBOL | LIMIT | UNIT |
|--|-------------------------|---|-----------------------------------|-------------|------|
| Drain-source voltage | | | V_{DS} | 600 | V |
| Gate-source voltage | | | V_{GS} | ± 30 | v |
| Continuous drain surrent /T 150 °C\ | V _{GS} at 10 V | T _C = 25 °C T _C = 100 °C | | 4.2 | |
| Continuous drain current (T _J = 150 °C) | VGS at 10 V | T _C = 100 °C | · I _D | 2.6 | A |
| Pulsed drain current ^a | | | I _{DM} | 5 | |
| Linear derating factor | | | | 0.5 | W/°C |
| Single pulse avalanche energy b | | | E _{AS} | 14 | mJ |
| Maximum power dissipation | | | P_{D} | 63 | W |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C |
| Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$ | | dv/dt | 70 | 1//20 | |
| Reverse diode dv/dt ^d | | | 3 | - V/ns | |
| Soldering recommendations (peak temperature) ^c For 10 s | | | 260 | °C | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 1 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



Vishay Siliconix

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R _{thJA} | - | 62 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 2.0 | C/VV |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|--|------|------|-------|------|
| Static | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 600 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | e to 25 °C, I _D = 1 mA | - | 0.68 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | · V _{GS} , I _D = 250 μA | 3.0 | - | 5.0 | V |
| Cata agurea lagkaga | | V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| Gate-source leakage | I_{GSS} | , | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 1 | μΑ |
| Zoro goto voltago droip ourrent | 1 | V _{DS} = | 600 V, V _{GS} = 0 V | - | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 480 V | , V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | $I_D = 0.5 A$ | - | 1.3 | 1.45 | Ω |
| Forward transconductance a | 9 _{fs} | V _{DS} : | = 20 V, I _D = 2.0 A | - | 0.8 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | | V _{GS} = 0 V, | - | 172 | - | |
| Output capacitance | C _{oss} | 7 | $V_{DS} = 100 \text{ V},$ | - | 19 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1 MHz | | - | 4 | - | |
| Effective output capacitance, energy related ^a | $C_{o(er)}$ | V 0VV 400V V 0V | | - | 12 | - | pF |
| Effective output capacitance, time related ^b | $C_{o(tr)}$ | V _{DS} = 0 | $V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$ | | 50 | - | |
| Total gate charge | Qg | | | - | 5 | 7.5 | |
| Gate-source charge | Q_{gs} | $V_{GS} = 10 \text{ V}$ | $V_{GS} = 10 \text{ V}$ $I_D = 2.0 \text{ A}, V_{DS} = 480 \text{ V}$ | | 1 | - | nC |
| Gate-drain charge | Q_gd | | | - | 3 | - | |
| Turn-on delay time | $t_{d(on)}$ | | | - | 10 | 20 | |
| Rise time | t _r | | $V_{DD} = 480 \text{ V}, I_{D} = 2.0 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$ | | 23 | 46 | ns |
| Turn-off delay time | $t_{d(off)}$ | V _{GS} = | | | 10 | 20 | 115 |
| Fall time | t _f | | | | 22 | 44 | |
| Gate input resistance | R_{g} | f = 1 MHz, open drain | | 2.1 | 4.2 | 8.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 4 | |
| Pulsed diode forward current | I _{SM} | | | - | - | 5 | A |
| Diode forward voltage | V _{SD} | T _J = 25 °C, I _S = 0.5 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | | | - | 222 | 444 | ns |
| Reverse recovery charge | Q _{rr} | $T_J = 25 ^{\circ}\text{C}$, $I_F = I_S = 0.5 \text{A}$, $di/dt = 100 \text{A/}\mu\text{s}$, $V_R = 25 \text{V}$ | | - | 0.8 | 1.6 | μC |
| Reverse recovery current | I _{RRM} | | | - | 5.6 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

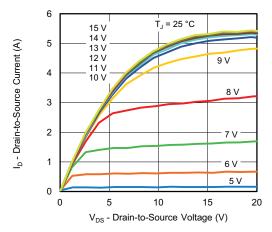


Fig. 1 - Typical Output Characteristics

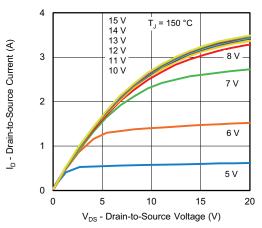


Fig. 2 - Typical Output Characteristics

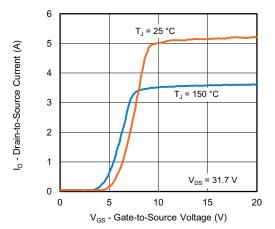


Fig. 3 - Typical Transfer Characteristics

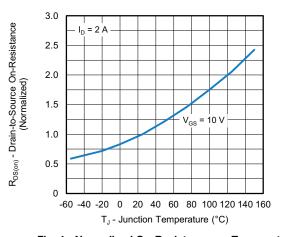


Fig. 4 - Normalized On-Resistance vs. Temperature

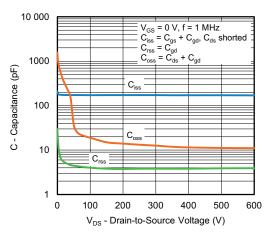


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

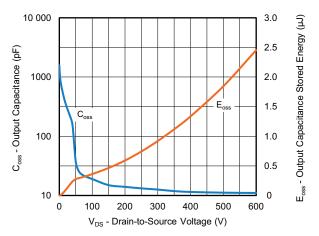


Fig. 6 - Coss and Eoss vs. VDS



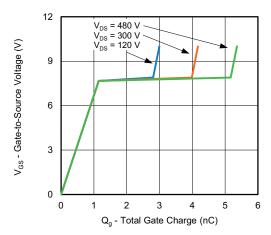


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

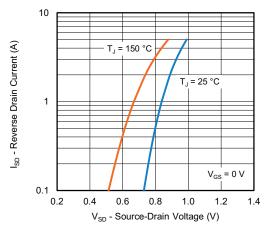


Fig. 8 - Typical Source-Drain Diode Forward Voltage

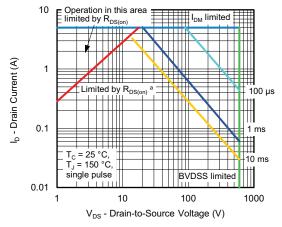


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

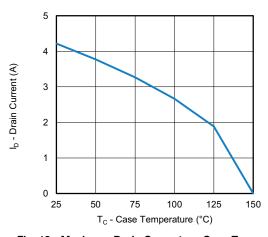


Fig. 10 - Maximum Drain Current vs. Case Temperature

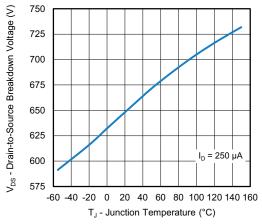


Fig. 11 - Temperature vs. Drain-to-Source Voltage



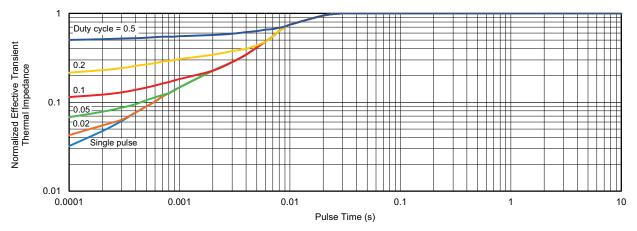


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

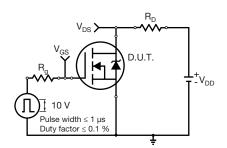


Fig. 13 - Switching Time Test Circuit

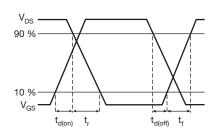


Fig. 14 - Switching Time Waveforms

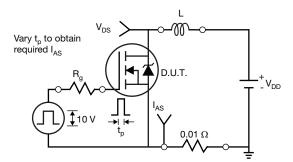


Fig. 15 - Unclamped Inductive Test Circuit

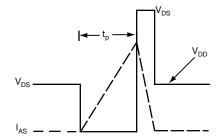


Fig. 16 - Unclamped Inductive Waveforms

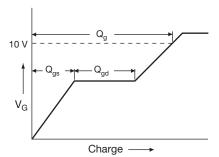


Fig. 17 - Basic Gate Charge Waveform

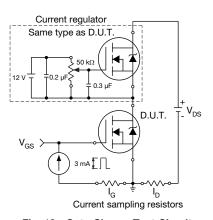
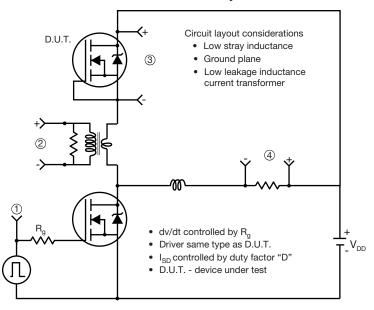


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



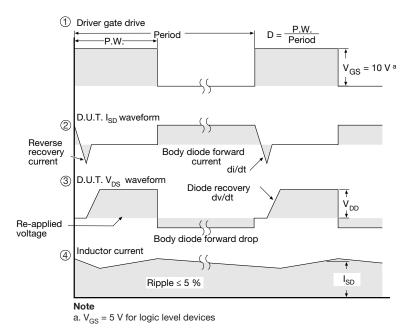


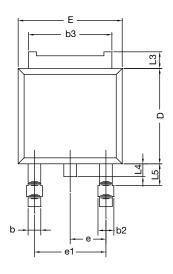
Fig. 19 - For N-Channel

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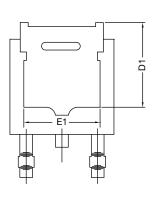


TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







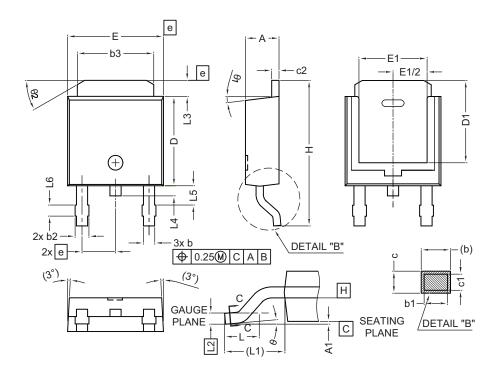
| | MILLIMETERS | | |
|------|-------------|-------|--|
| DIM. | MIN. | MAX. | |
| A | 2.18 | 2.38 | |
| A1 | - | 0.127 | |
| b | 0.64 | 0.88 | |
| b2 | 0.76 | 1.14 | |
| b3 | 4.95 | 5.46 | |
| С | 0.46 | 0.61 | |
| C2 | 0.46 | 0.89 | |
| D | 5.97 | 6.22 | |
| D1 | 4.10 | - | |
| Е | 6.35 | 6.73 | |
| E1 | 4.32 | - | |
| Н | 9.40 | 10.41 | |
| е | 2.28 | BSC | |
| e1 | 4.56 BSC | | |
| L | 1.40 | 1.78 | |
| L3 | 0.89 | 1.27 | |
| L4 | - | 1.02 | |
| L5 | 1.01 | 1.52 | |

Note

• Dimension L3 is for reference only



VERSION 2: FACILITY CODE = N



| | MILLIMETERS | | |
|------|-------------|-------|--|
| DIM. | MIN. | MAX. | |
| Α | 2.18 | 2.39 | |
| A1 | - | 0.13 | |
| b | 0.65 | 0.89 | |
| b1 | 0.64 | 0.79 | |
| b2 | 0.76 | 1.13 | |
| b3 | 4.95 | 5.46 | |
| С | 0.46 | 0.61 | |
| c1 | 0.41 | 0.56 | |
| c2 | 0.46 | 0.60 | |
| D | 5.97 | 6.22 | |
| D1 | 5.21 | = | |
| E | 6.35 | 6.73 | |
| E1 | 4.32 - | | |
| е | 2.29 BSC | | |
| Н | 9.94 | 10.34 | |

| | MILLIMETERS | | |
|------|-------------|--------|--|
| DIM. | MIN. | MAX. | |
| L | 1.50 | 1.78 | |
| L1 | 2.74 | ł ref. | |
| L2 | 0.51 | BSC | |
| L3 | 0.89 | 1.27 | |
| L4 | - | 1.02 | |
| L5 | 1.14 | 1.49 | |
| L6 | 0.65 | 0.85 | |
| θ | 0° | 10° | |
| θ1 | 0° | 15° | |
| θ2 | 25° | 35° | |

Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E19-0649-Rev. Q, 16-Dec-2019

DWG: 5347



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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